

JST136W-600E 1A TRIAC

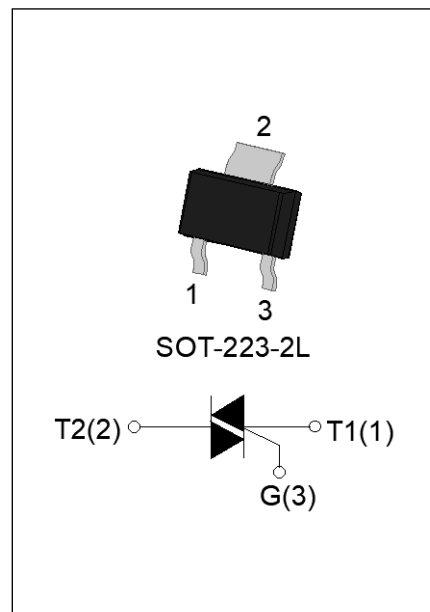
Rev.A.1.1

DESCRIPTION:

The JST136W-600E triac is suitable for general purpose AC switching. It can be used as an ON/OFF function in applications such as heating regulation, induction motor starting circuits, for phase control operation in light dimmers, motor speed controllers. Package SOT-223-2L is RoHS compliant.

MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	1	A
V_{DRM}/V_{RRM}	600	V
$I_{GT\ I/II/III/IV}$	10/10/10/25	mA


ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T _{stg}	-40-150	℃
Operating junction temperature range		T _j	-40-125	℃
Repetitive peak off-state voltage (T _j =25℃)		V _{DRM}	600	V
Repetitive peak reverse voltage (T _j =25℃)		V _{RRM}	600	V
RMS on-state current (T _c ≤107℃)		I _{T(RMS)}	1	A
Non repetitive surge peak on-state current (full cycle , t _p =20ms , T _j =25℃)		I _{TSM}	25	A
Non repetitive surge peak on-state current (full cycle , t _p =16.6ms , T _j =25℃)			27.5	
I ² t value for fusing (t _p =10ms , T _j =25℃)		I ² t	3.125	A ² s
Critical rate of rise of on-state current (I _G =2×I _{GT} , f=100Hz , T _j =125℃)	I - II -III	di/dt	80	A/μs
	IV		40	
Peak gate current (t _p =20μs , T _j =125℃)		I _{GM}	2	A
Average gate power dissipation (T _j =125℃)		P _{G(AV)}	0.5	W
Peak gate power		P _{GM}	5	W
Peak pulse voltage (T _j =25℃; non-repetitive,off-state;FIG.8)		V _{pp}	3.5	kV

ELECTRICAL CHARACTERISTICS ($T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Test Condition	Quadrant	Value		Unit
I_{GT}	$V_D=12\text{V}$ $R_L=33\Omega$	I - II - III	MAX.	10	mA
		IV		25	
V_{GT}		ALL	MAX.	1.3	V
V_{GD}	$V_D=V_{DRM}$ $T_j=125^{\circ}\text{C}$ $R_L=3.3\text{k}\Omega$	ALL	MIN.	0.2	V
I_L	$I_G=1.2I_{GT}$	I - III	MAX.	20	mA
		II - IV		30	
I_H	$I_T=100\text{mA}$		MAX.	15	mA
dV/dt	$V_D=400\text{V}$ Gate Open $T_j=110^{\circ}\text{C}$		MIN.	300	$\text{V}/\mu\text{s}$
$(dV/dt)_c$	$(dI/dt)_c=1.8\text{A/ms}$, $T_j=110^{\circ}\text{C}$		MIN.	6	$\text{V}/\mu\text{s}$
t_{on}	$I_G=40\text{mA}$ $I_A=200\text{mA}$ $I_R=20\text{mA}$ $T_j=25^{\circ}\text{C}$		TYP.	1.5	μs
t_{off}				15	

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX.)	Unit
V_{TM}	$I_{TM}=5\text{A}$ $t_p=380\mu\text{s}$	$T_j=25^{\circ}\text{C}$	1.7	V
V_{TO}	Threshold voltage	$T_j=125^{\circ}\text{C}$	0.94	V
R_D	Dynamic resistance	$T_j=125^{\circ}\text{C}$	124	$\text{m}\Omega$
I_{DRM}	$V_D=V_{DRM}$ $V_R=V_{RRM}$	$T_j=25^{\circ}\text{C}$	5	μA
I_{RRM}		$T_j=125^{\circ}\text{C}$	0.3	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	junction to case (AC)	15	$^{\circ}\text{C}/\text{W}$
$R_{th(j-a)}$	junction to ambient (AC)	150	$^{\circ}\text{C}/\text{W}$

ORDERING INFORMATION

J	ST	136	W	-600	E
JieJie Microelectronics Co., Ltd.	Triacs	$I_{T(RMS)}:1A$			$E:I_{GT1-3}\leq 10mA\ I_{GT4}\leq 25mA$
		W:SOT-223-2L		600: $V_{DRM}\ /V_{RRM}\geq 600V$	

MARKING

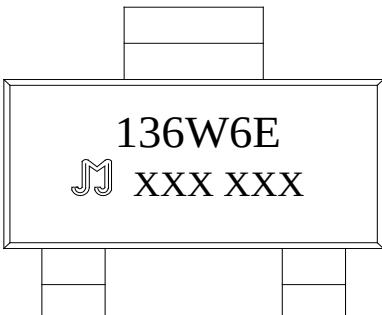
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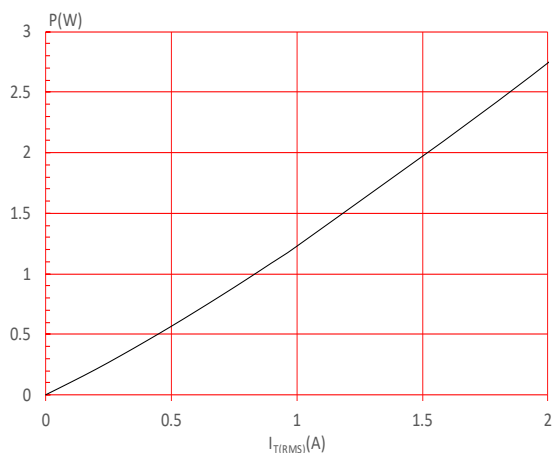
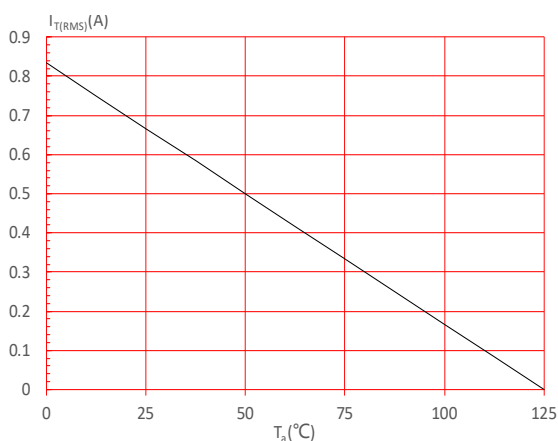
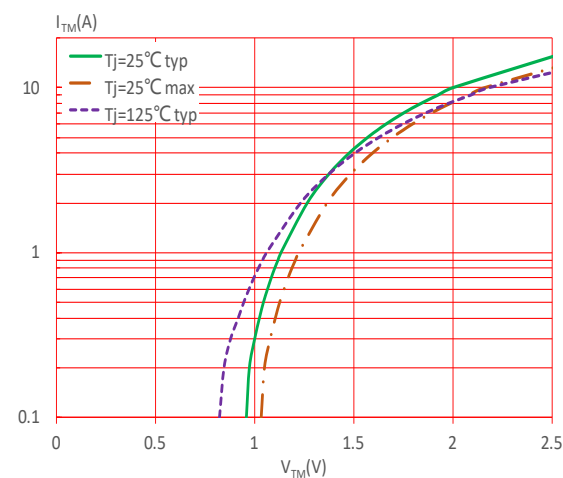
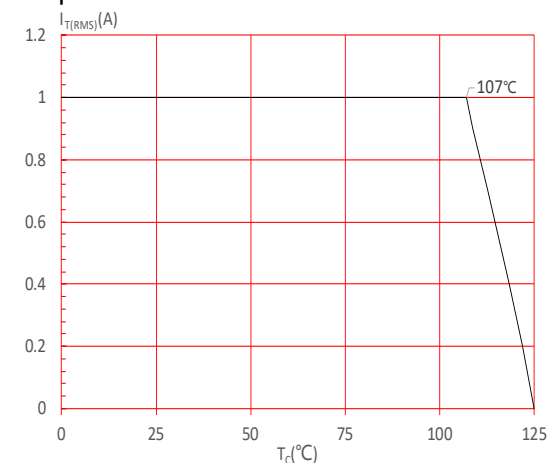
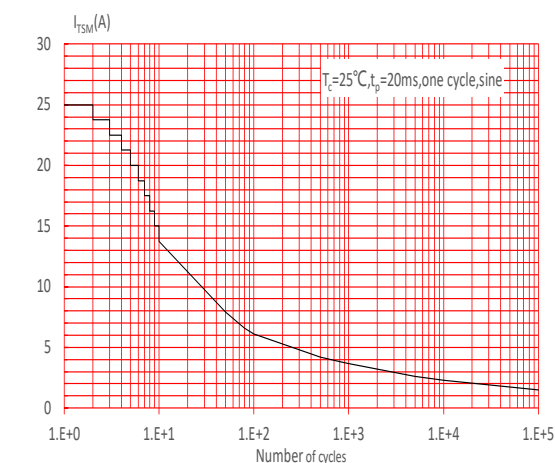
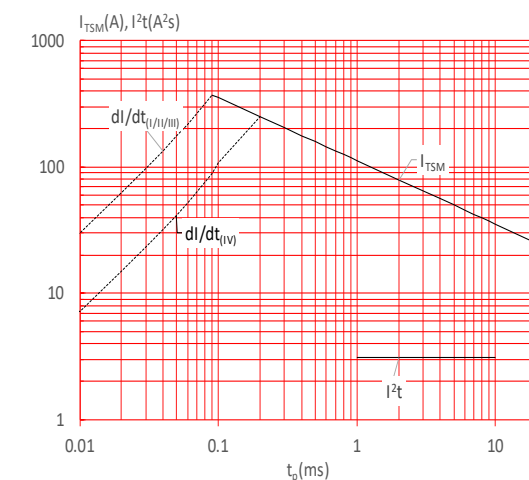
FIG.1: Maximum power dissipation versus RMS on-state current

FIG.3: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35 μ m) (full cycle)

FIG.5: On-state characteristics

FIG.2: RMS on-state current versus case temperature

FIG.4: Surge peak on-state current versus number of cycles

FIG.6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20ms$, and corresponding value of I^2t (I - II - III: $dI/dt < 80A/\mu s$; IV: $dI/dt < 40A/\mu s$)


FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

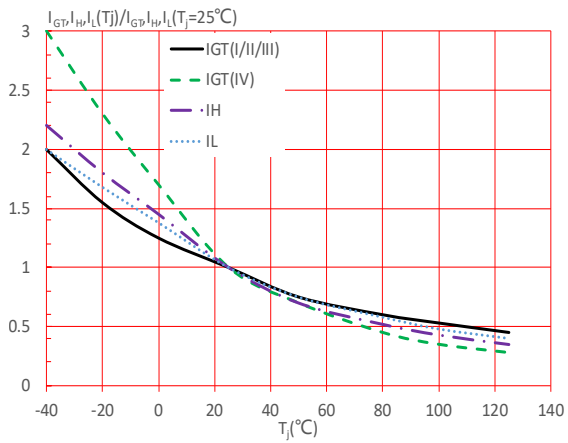
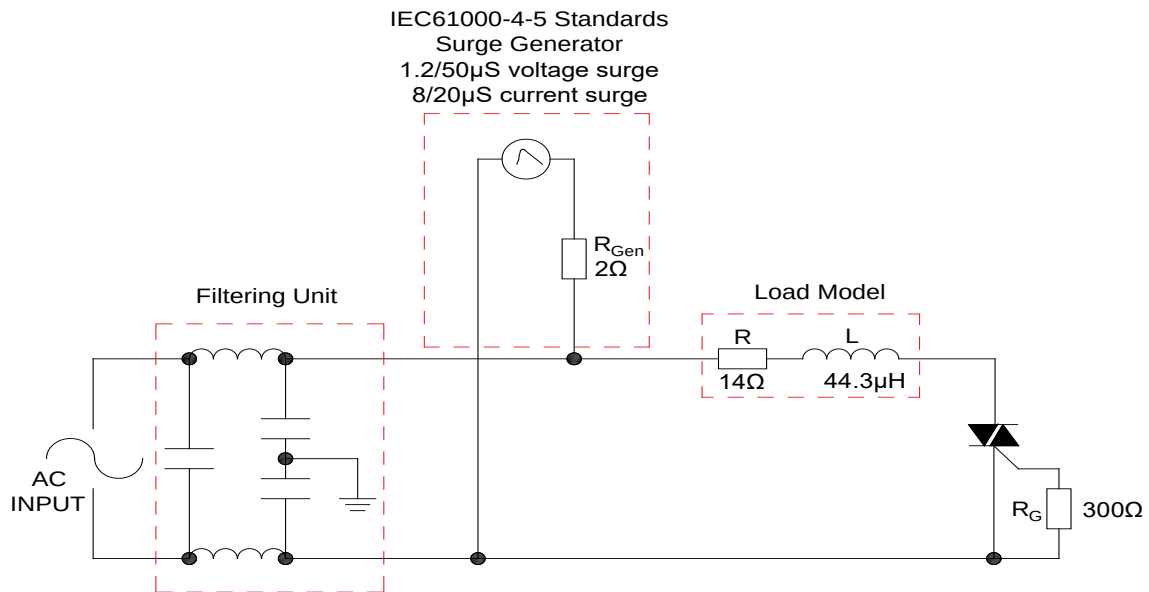
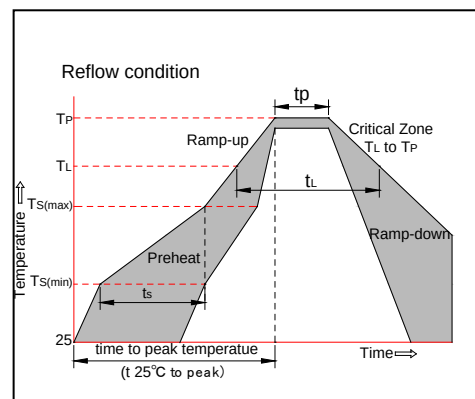


FIG.8: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (T _{s(min)})	+150°C
	-Temperature Max(T _{s(max)})	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T _L) to peak)		3°C/sec. Max
T _{s(max)} to T _L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T _L) (Liquidus)	+217°C
	-Temperature(t _L)	60-150 secs.
Peak Temp (T _p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t _p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T _p)		8 min. Max
Do not exceed		+260°C



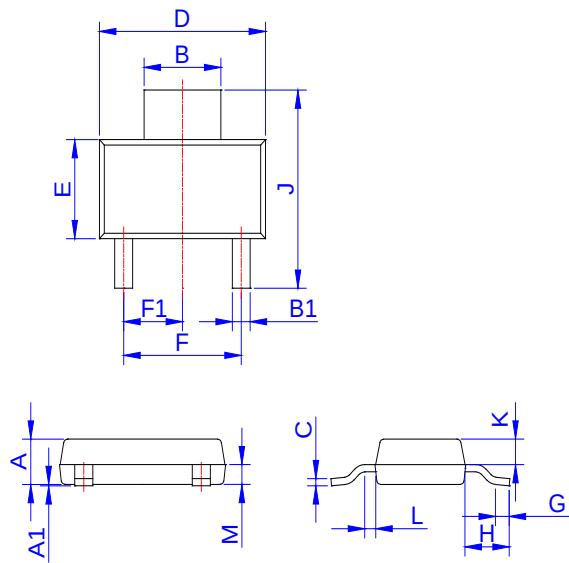
ORDERING INFORMATION

Order code	Voltage $V_{\text{DRM}}/V_{\text{RRM}}$ (V)	IGT(mA)		Package	Base qty. (pcs)	Delivery mode
		I - II - III	IV			
JST136W-600E	600	10	25	SOT-223-2L	4,000	Tape & Reel

Document Revision History

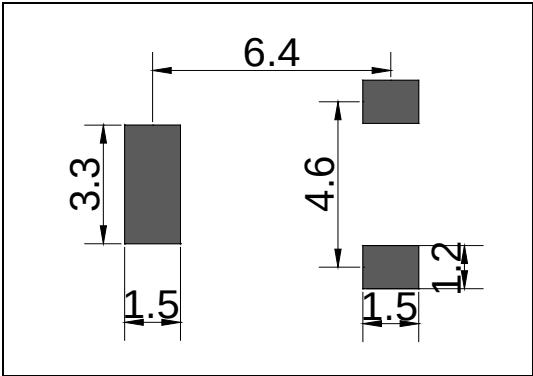
Date	Revision	Changes
Apr.14, 2023	A.1.0	Last updated
Oct.24, 2025	A.1.1	Revise PACKAGE MECHANICAL DATA

PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.50	1.60	1.80	0.059	0.063	0.071
A1	0.01	0.06	0.10	0.001	0.002	0.004
B	2.90	3.00	3.10	0.114	0.118	0.122
B1	0.60	0.70	0.80	0.024	0.028	0.031
C	0.22	0.254	0.32	0.009	0.010	0.013
D	6.30	6.50	6.70	0.248	0.256	0.264
E	3.30	3.50	3.70	0.130	0.138	0.146
F	4.40		4.80	0.173		0.189
F1	2.20		2.40	0.087		0.094
G	0.50		1.00	0.020		0.039
H	1.50	1.75	2.00	0.059	0.069	0.079
J	6.70	7.00	7.30	0.264	0.276	0.287
K	0.80		1.00	0.031		0.039
L	0.40		0.80	0.016		0.031
M	0.75		0.95	0.030		0.037

FOOTPRINT-SOT-223-2L (dimensions in mm)



Technical drawing of a 6-hole circular plate. The drawing includes three views: a top view, a side view (B-B), and a cross-section view (A-A).

Top View: Shows a circular plate with six holes arranged in a hexagonal pattern. The overall diameter is $\phi 330^{+2.2}$. The distance between the centers of adjacent holes is $P1$. The distance from the center of a hole to the outer edge is $P0$. The thickness of the plate is 2.3 ± 0.2 . The inner diameter of the central hole is $\phi \text{min} 12.8$. The distance from the center of a hole to the center of the plate is $A0$. The angle between the center line and the edge is 8° .

Side View (B-B): Shows the profile of the plate. The total thickness is T . The distance from the top surface to the center of the holes is $B0$. The distance from the bottom surface to the center of the holes is $K0$. The distance from the center of the holes to the outer edge is B .

Cross-section View (A-A): Shows the internal structure of the plate. The thickness is 100 ± 0.5 . The distance from the top surface to the center of the holes is 1.96 ± 0.2 . The distance from the bottom surface to the center of the holes is 16.72 ± 0.3 . The distance from the center of the holes to the outer edge is 12.8 ± 0.5 .

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	-	-	12.30	-		0.482
E	1.65	1.75	1.85	0.065	0.069	0.073
F	5.45	5.50	5.55	0.215	0.217	0.219
D0	1.50	1.55	1.60	0.059	0.061	0.063
D1	1.50	-	-	0.059	-	-
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.95	2.00	2.05	0.077	0.079	0.081
10P0	39.80	40.00	40.20	1.567	1.575	1.583
A0	6.85	6.95	7.05	0.269	0.273	0.276
B0	7.15	7.25	7.35	0.280	0.284	0.288
K0	1.95	2.05	2.15	0.076	0.080	0.084
T	0.20	0.25	0.30	0.008	0.010	0.012

PACKAGE	OUTLINE	REEL (PCS)	PER CARTON (PCS)	TAPE & REEL
SOT-223-2L	TAPING	4,000	40,000	13 inch

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